

ABSTRACT OF THE DISCLOSURE

A probe card for testing an electrical element such as a semiconductor wafer or a printed wiring board includes a substrate with circuitry thereon, an encapsulant layer overlying the substrate and a multiplicity of leads extending upwardly from the substrate through the encapsulant layer to terminals, the terminals projecting above the encapsulant layer. The probe card can be engaged with the electronic element so that the tips of the leads bear on the contact pads of the electronic element, and so that the leads and encapsulant layer deform to accommodate irregularities in the electronic element or probe card. The card can be made by providing the substrate, a sacrificial layer and leads extending between the sacrificial layer and substrate, moving the substrate and sacrificial layer away from one another to deform the leads and injecting a curable material around the leads to form the encapsulant layer.